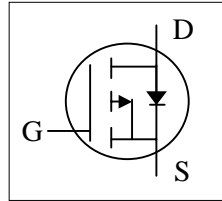




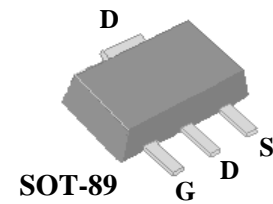
- ▼ Simple Drive Requirement
- ▼ Small Package Outline
- ▼ Capable of 2.5V Gate Drive
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	-20V
$R_{DS(ON)}$	135m $\Omega$
$I_D$	-2.3A

## Description

AP9451 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.



## Absolute Maximum Ratings @ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_A=25^\circ\text{C}$	Drain Current, $V_{GS} @ 4.5V^3$	-2.3	A
$I_D @ T_A=70^\circ\text{C}$	Drain Current, $V_{GS} @ 4.5V^3$	-1.9	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-12	A
$P_D @ T_A=25^\circ\text{C}$	Total Power Dissipation	1.25	W
	Linear Derating Factor	0.01	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	100	$^\circ\text{C}/\text{W}$



# AP9451GG-HF

## Electrical Characteristics @T<sub>j</sub>=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-20	-	-	V
ΔBV <sub>DSS</sub> /ΔT <sub>j</sub>	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	-	-0.02	-	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2.3A	-	-	135	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-1.0A	-	-	240	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.5	-	-1.5	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-2.3A	-	2.3	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V	-	-	-1	uA
	Drain-Source Leakage Current (T <sub>j</sub> =70°C)	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V	-	-	-25	uA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	-	-	±100	nA
Q <sub>g</sub>	Total Gate Charge <sup>2</sup>	I <sub>D</sub> = -2.3A	-	5.5	9	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> = -15V	-	1	-	nC
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	V <sub>GS</sub> = -4.5V	-	2.5	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time <sup>2</sup>	V <sub>DS</sub> =-10V	-	9	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =-1A	-	25	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =3.3Ω	-	20	-	ns
t <sub>f</sub>	Fall Time	V <sub>GS</sub> =-5V	-	10	-	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	270	430	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = -20V	-	100	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	35	-	pF
R <sub>g</sub>	Gate Resistance	f=1.0MHz	-	8	12	Ω

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V <sub>SD</sub>	Forward On Voltage <sup>2</sup>	T <sub>j</sub> =25°C, I <sub>S</sub> =-1A, V <sub>GS</sub> =0V	-	-	-1.6	V
t <sub>rr</sub>	Reverse Recovery Time <sup>2</sup>	I <sub>S</sub> = -2.5A, V <sub>GS</sub> =0V, dI/dt=100A/μs	-	27	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	27	-	nC

### Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mount on FR4 board, t ≤ 10s.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

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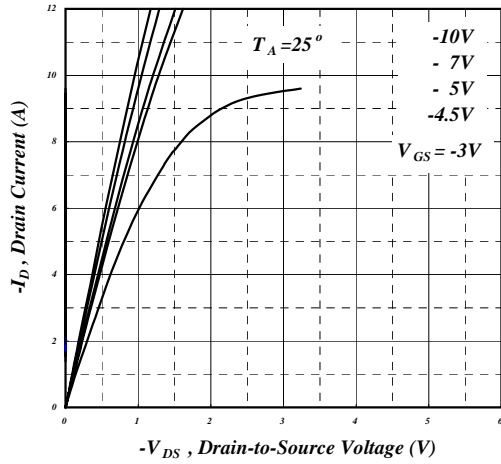


Fig 1. Typical Output Characteristics

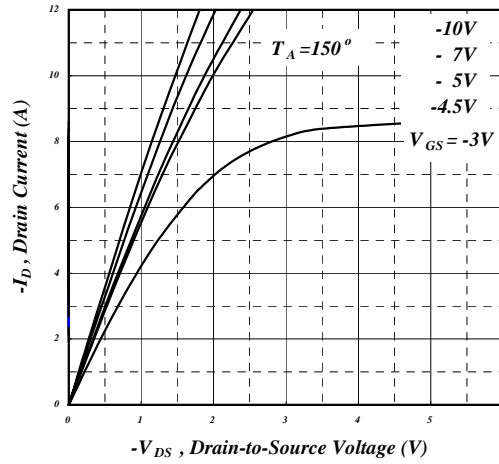


Fig 2. Typical Output Characteristics

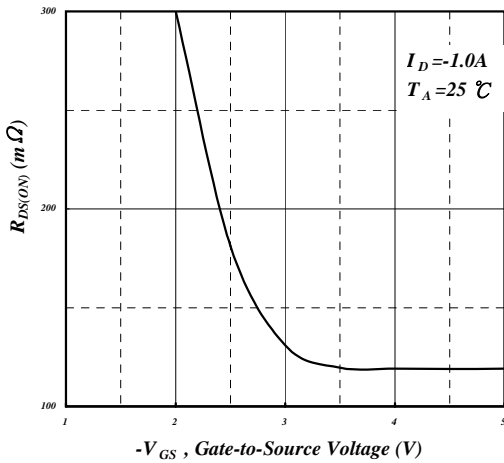


Fig 3. On-Resistance v.s. Gate Voltage

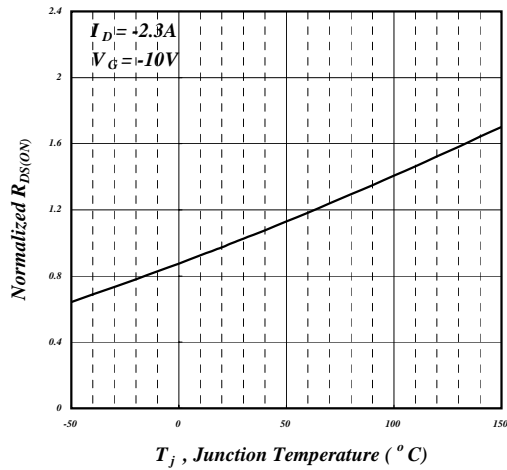


Fig 4. Normalized On-Resistance

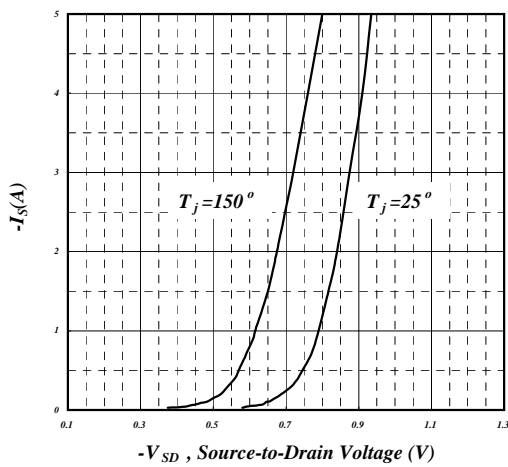


Fig 5. Forward Characteristic of Reverse Diode

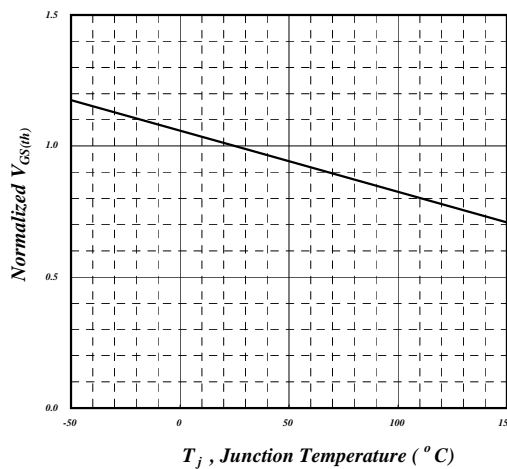


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

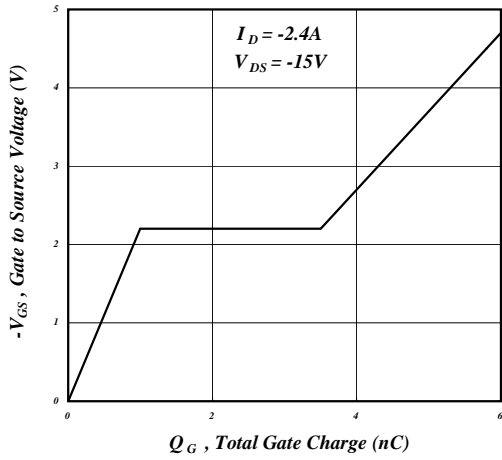


Fig 7. Gate Charge Characteristics

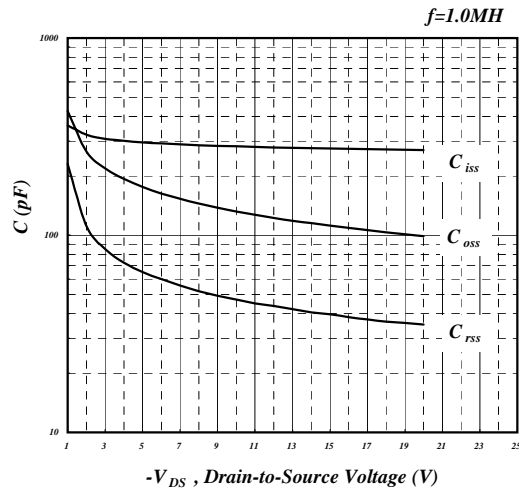


Fig 8. Typical Capacitance Characteristics

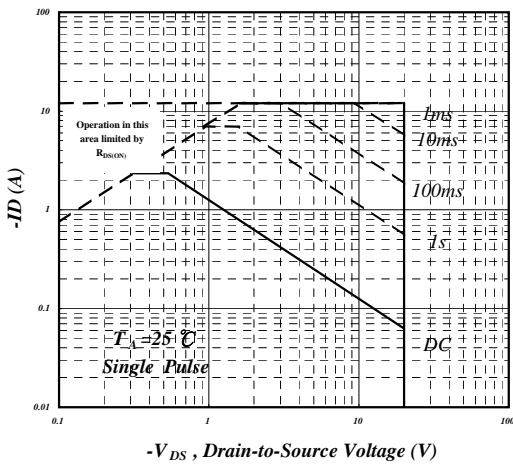


Fig 9. Maximum Safe Operating Area

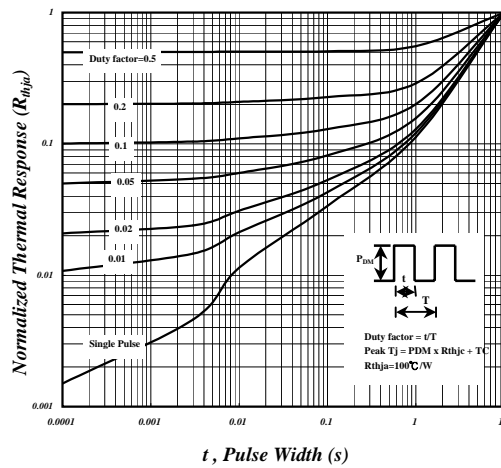


Fig 10. Effective Transient Thermal Impedance

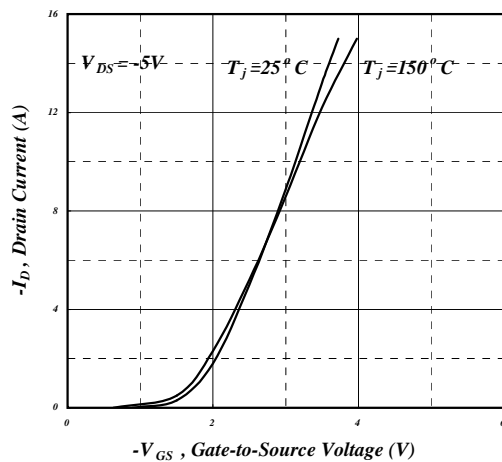


Fig 11. Transfer Characteristics

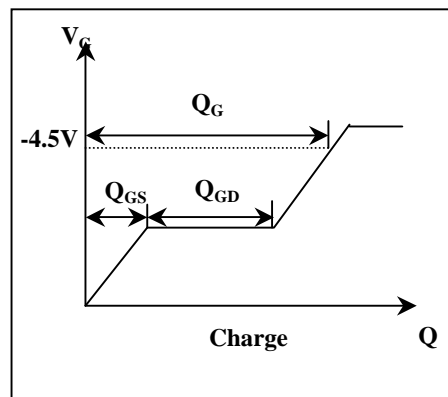
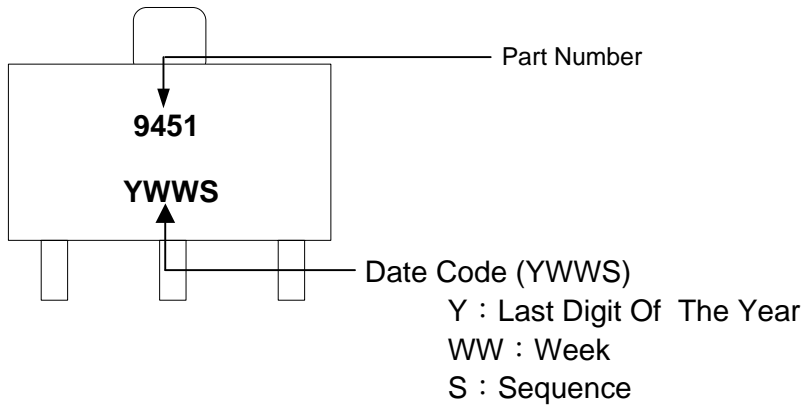


Fig 12. Gate Charge Waveform



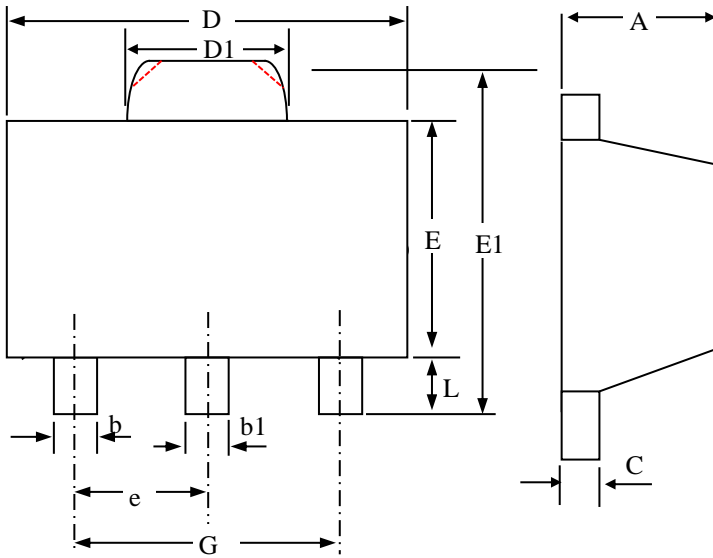
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**MARKING INFORMATION**





## Package Outline & Packing : SOT-89



SYMBOLS	Millimeters		
	MIN	NOM	MAX
b	0.30	0.43	0.55
b1	0.40	0.50	0.60
D1	1.40	1.60	1.80
D	4.40	4.50	4.60
E	2.30	2.45	2.60
E1	3.80	4.05	4.30
e	1.30	1.50	1.70
G	2.80	3.00	3.20
A	1.40	1.50	1.60
C	0.34	0.39	0.44
L	0.80	1.00	1.20

- 1.All Dimensions Are in Millimeters.
- 2.Dimension Does Not Include Mold Protrusions.
- 3.Two package structure , obtuse angle and circular bead,is acceptable.



SOT-89 FOOTPRINT :

